

100A 1700V Half bridge module

1 Description

These Insulated Gate Bipolar Transistor used advanced trench and Fieldstop technology design, provided excellent $V_{CE(sat)}$ and switching speed ,low gate charge. Which accords with the RoHS standard.

2 Features

- FS Trench Technology, Positive temperature coefficient
- Low saturation voltage: $V_{CE(sat)}$, typ = 2.25V @ $I_C = 100A$ and $T_j = 25^\circ C$
- Extremely enhanced avalanche capability

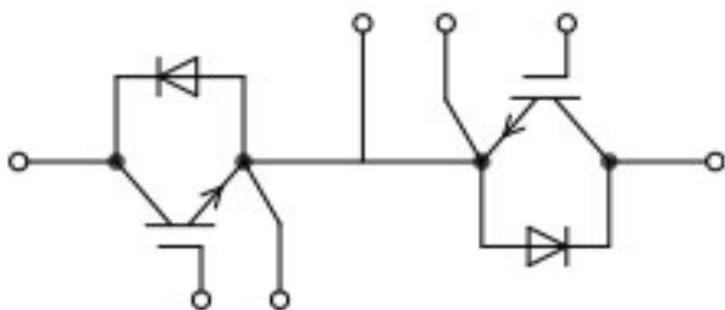


3 Applications

- Welding
- UPS
- Three-leve Inverter
- AC and DC servo drive amplifier

Type	V_{CE}	I_C	$V_{CE(sat)}, T_j=25^\circ C$	T_{jop}	Package
DGA100H170M2T	1700V	100A ($T_j=100^\circ C$)	2.25V (Typ)	175°C	34MM

4 Equivalent Circuit Schematic



5 Electrical Characteristics

5.1 Absolute Maximum Ratings (IGBT) (Tc=25°C,unless otherwise specified)

Parameter	Symbol	Value	Units
Collector-to-Emitter Voltage	V _{CE}	1700	V
Gate-to-Emitter Voltage	V _{GE}	±20	V
DC Collector current	I _C	200	A
T _j =100°C		100	A
Pulsed Collector Current #1	I _{CM}	400	A

Notes: #1 Pulse duration is limited by T_{j,max}

5.2 Absolute Maximum Ratings (Diode) (Tc=25°C,unless otherwise specified)

PARAMETER	SYMBOL	VALUE	UNIT
Peak Repetitive Reverse Voltage	V _{RRM}	1700	V
DC Blocking Voltage	V _R	1700	V
Average Rectified Forward Current	I _{F(AV)}	100	A
Repetitive Peak Surge Current	I _{FRM}	200	A
Nonrepetitive Peak Surge Current(single)	I _{FSM}	500	A

5.3 IGBT Module

Parameter	Symbol	VALUE	Units
Junction Temperature Range	T _{jmax}	-45~175	°C
Operating Junction Temperature	T _{jop}	-45~150	°C
Storage Temperature Range	T _{stg}	-45~150	°C
Isolation Voltage R _{MS} ,f=50Hz,t=1min	V _{ISO}	4000	V

5.4 Thermal Characteristics (IGBT Module)

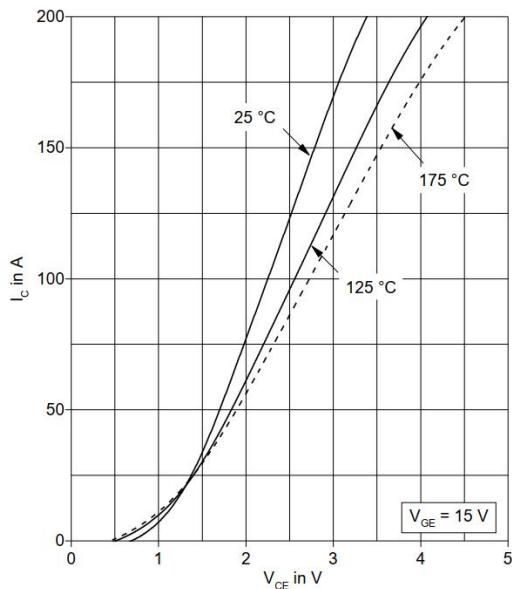
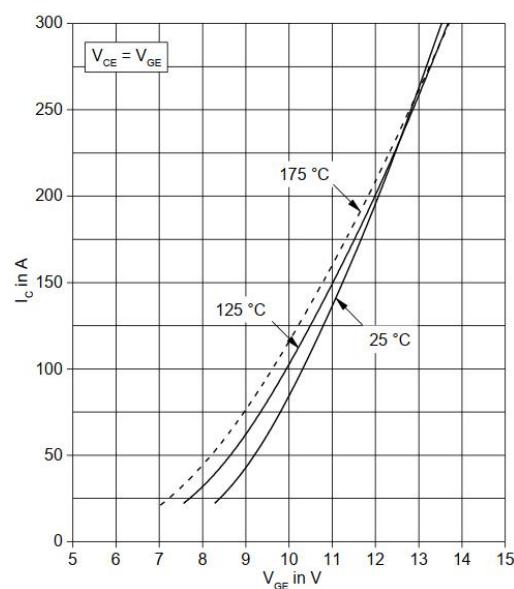
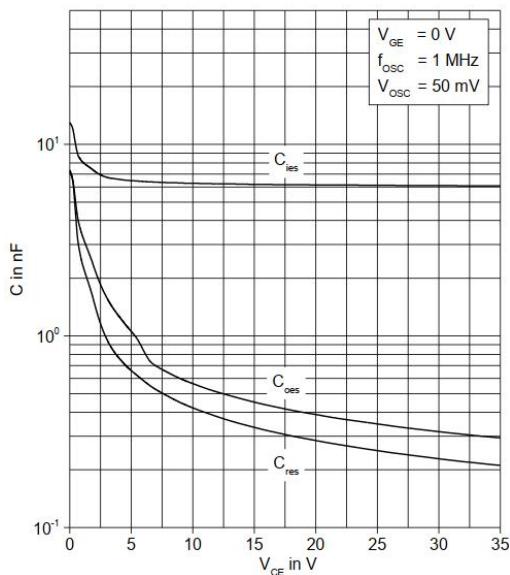
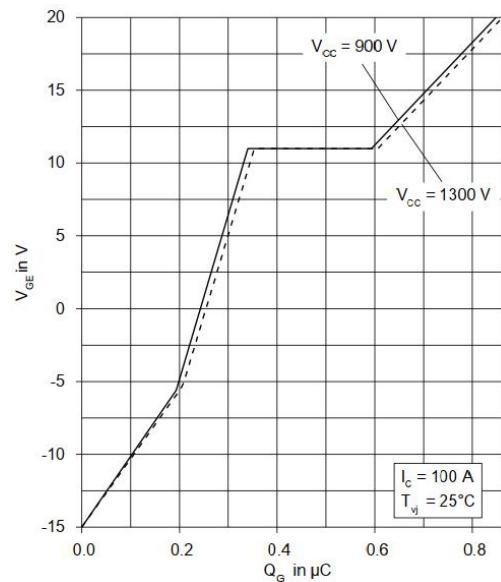
Parameter	Symbol	Rating	Units
Thermal Resistance Junction to Case	IGBT R _{thJC}	0.22	°C/W
Diode		0.42	

5.5 Electrical Characteristics (IGBT) ($T_c=25^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Conditions	Value			Units
			Min	Typ	Max	
Static Characteristics						
Collector-to-Emitter Breakdown Voltage	$V_{(\text{BR})\text{CES}}$	$I_C=1\text{mA}, V_{GE}=0\text{V}, T_j=25^\circ\text{C}$	1700	--	--	V
Collector-to-Emitter Leakage Current	I_{CES}	$V_{CE}=1700\text{V}, V_{GE}=0\text{V}, T_j=25^\circ\text{C}$	--	--	100	μA
		$V_{CE}=1700\text{V}, V_{GE}=0\text{V}, T_j=125^\circ\text{C}$	--	200	--	μA
		$V_{CE}=1700\text{V}, V_{GE}=0\text{V}, T_j=175^\circ\text{C}$	--	4.0	--	mA
Gate-to-Emitter Leakage Current	I_{GES}	$V_{GE}=\pm 20\text{V}, V_{CE}=0\text{V}, T_j=25^\circ\text{C}$	--	--	± 500	nA
		$V_{GE}=\pm 20\text{V}, V_{CE}=0\text{V}, T_j=150^\circ\text{C}$	--	--	± 1.0	μA
Gate Threshold Voltage	$V_{GE(\text{th})}$	$V_{CE}=V_{GE}, I_C=6\text{mA}$	4.5	-	6.5	V
Collector-emitter saturation voltage	$V_{CE\text{sat}}$	$V_{GE}=15\text{V}, I_C=100\text{A}, T_j=25^\circ\text{C}$	--	2.25	2.6	V
		$V_{GE}=15\text{V}, I_C=100\text{A}, T_j=125^\circ\text{C}$	--	2.55	--	V
		$V_{GE}=15\text{V}, I_C=100\text{A}, T_j=175^\circ\text{C}$	--	2.75	--	V
Internal gate resistance	R_{Gint}		--	5.9	--	Ω
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{CE}=25\text{V}, V_{GE}=0\text{V}, f=1\text{MHz}, T_a=25^\circ\text{C}$	--	6100	--	pF
Output Capacitance	C_{oss}		--	350	--	
Reverse Transfer Capacitance	C_{rss}		--	240	--	
IGBT Characteristics						
Turn-on delay time	$t_{d(on)}$	$V_{CE}=900\text{V}, I_C=100\text{A}, R_g=4.4\Omega, V_{GE}=15\text{V}, \text{感性负载}, T_j=25^\circ\text{C}$	--	195	--	nS
Rise time	t_r		--	70	--	nS
Turn-off delay time	$t_{d(off)}$		--	250	--	nS
Fall time	t_f		--	160	--	nS
Turn-on energy	E_{on}		--	23	--	mJ
Turn-off energy	E_{off}		--	15	--	mJ
Total switching energy	E_{ts}		--	38	--	mJ
Turn-on delay time	$t_{d(on)}$	$V_{CE}=900\text{V}, I_C=100\text{A}, R_g=4.4\Omega, V_{GE}=15\text{V}, \text{感性负载}, T_j=175^\circ\text{C}$	--	210	--	nS
Rise time	t_r		--	80	--	nS
Turn-off delay time	$t_{d(off)}$		--	320	--	nS
Fall time	t_f		--	200	--	nS
Turn-on energy	E_{on}		--	38	--	mJ
Turn-off energy	E_{off}		--	33	--	mJ
Total switching energy	E_{ts}		--	71	--	mJ
Gate charge	Q_g	$V_{CE}=900\text{V}, I_C=100\text{A}, V_{GE}=15\text{V}$	--	700	--	nC
Short circuit current	I_{sc}	$t_{psc} \leq 10 \mu\text{s}, V_{GE} = 15 \text{ V}, T_{vj} = 175^\circ\text{C}, V_{CC} = 1300 \text{ V}, V_{CEM} \text{ CHIP} \leq 1700 \text{ V}$	--	310	--	A

5.6 Electrical Characteristics (Diode) ($T_c=25^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Conditions	Value			Units
			Min	Typ	Max	
Diode forward voltage	V_F	$I_F=100\text{A}, T_j=25^\circ\text{C}$	--	1.8	2.3	V
		$I_F=100\text{A}, T_j=150^\circ\text{C}$	--	1.9	--	V
Diode reverse recovery time	t_{rr}	$I_F=100\text{A},$ $\frac{di}{dt}=1300\text{A/uS}$, $V_R=900\text{V}$	--	540	--	ns
Diode peak reverse recovery current	I_{rrm}		--	90	--	A
Diode reverse recovery charge	Q_{rr}	$V_R=900\text{V}$ $V_R=1700\text{V}, T_c = 150^\circ\text{C}$	--	29	--	uC
Maximum Instantaneous Reverse	I_R		--	--	100	uA
			--	1.8	--	mA

6 Typical Characteristic Curves

Fig1. Typical on-state characteristics, chip level

Fig2. Typical transfer characteristics, chip level

Fig3. Typical capacitance as a function of collector-emitter voltage

Fig14. Typical gate charge

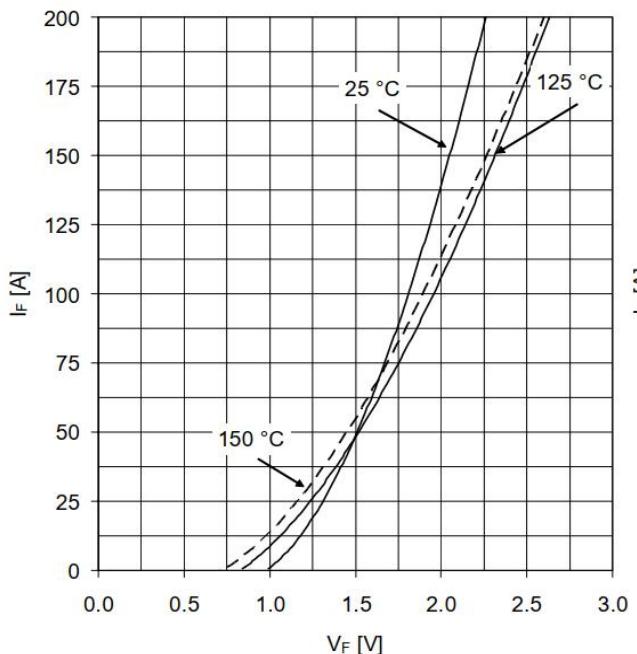


Fig5.Typical diode forward characteristics, chip level

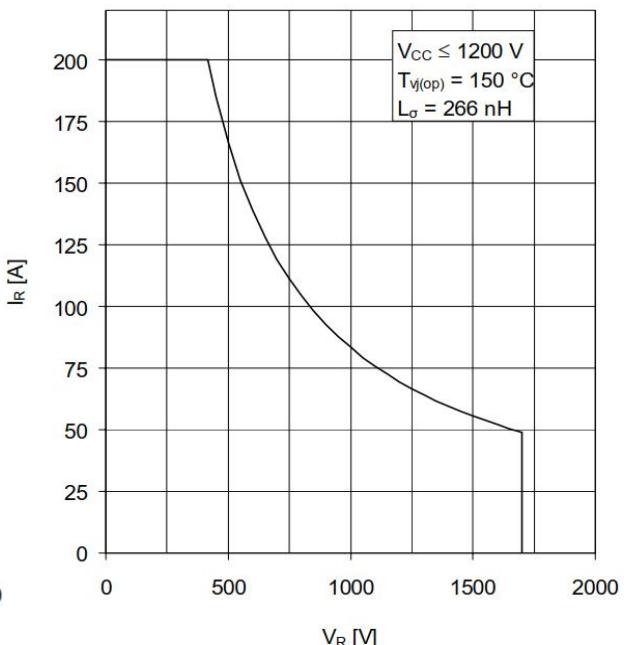


Fig6.Safe operating area (FBSOA)

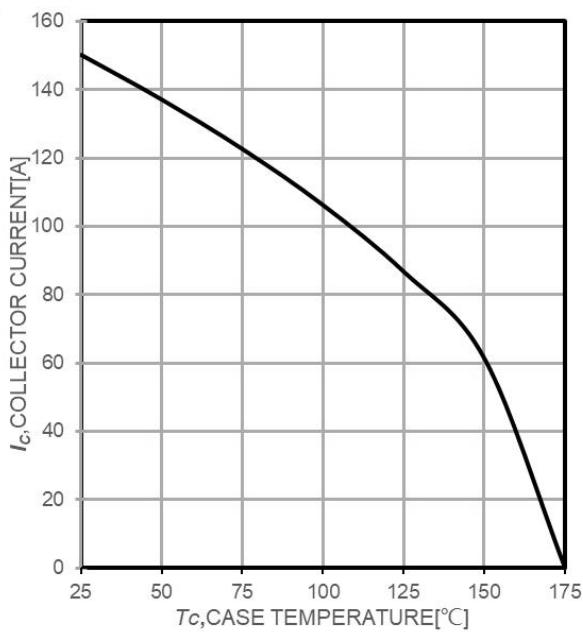


Fig7. Collector current as a function of case temperature ($V_{GE}=15$ V)

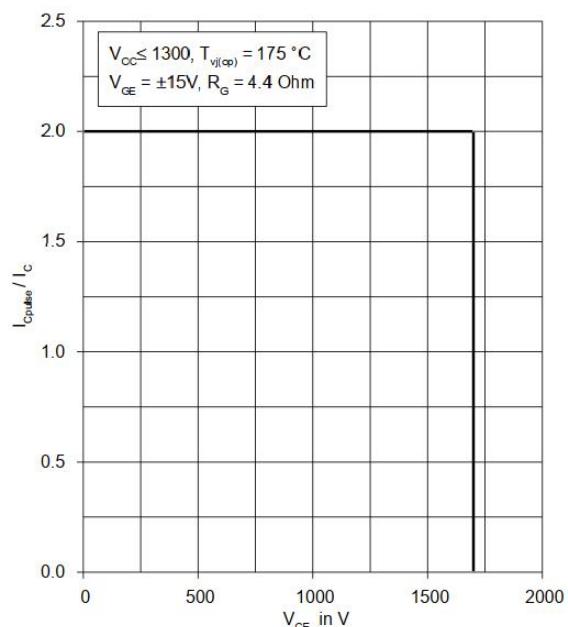
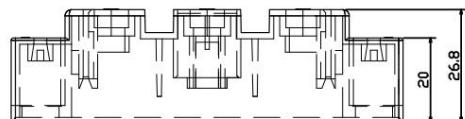
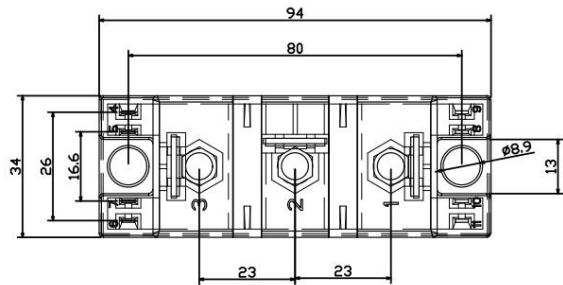
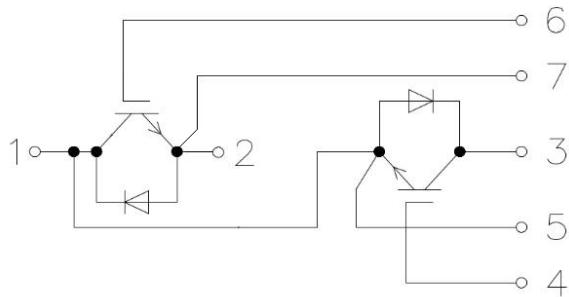


Fig8.Safe operation area (RBSOA)

7 Dimensions



7.1 Circuit Schematic



8 Attentions

- Jiangsu Donghai Semiconductor Technology CO.,LTD. reserves the right to change the specification without prior notice! The customer should obtain the latest version of the information before making the order and verify that the information is complete and up to date.
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- Product promotion is endless, our company will be dedicated to provide customers with better products.

9 Appendix

Revision history:

Date	REV.	Description	Page
2023.2.8	1.0	Original	